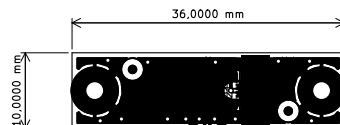
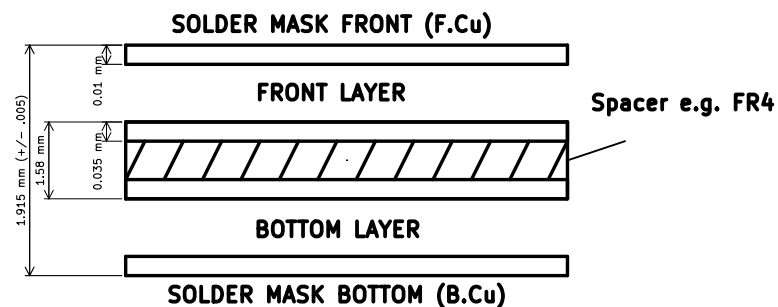


GENERAL NOTES



| Layer Name | Type | Material | Thickness (mm) | Recommended Color | Epsilon R | Loss Tangent |
|--------------|---------------------|---------------|----------------|-------------------|-----------|--------------|
| F.Silkscreen | Top Silk Screen | Not specified | 0 mm | White | 1 | 0 |
| F.Paste | Top Solder Paste | | 0 mm | | 1 | 0 |
| F.Mask | Top Solder Mask | Not specified | 0,01 mm | Red | 3,3 | 0 |
| F.Cu | copper | | 0,035 mm | | 1 | 0 |
| Dielectric 1 | core | FR4 | 1,51 mm | | 4,5 | 0,02 |
| B.Cu | copper | | 0,035 mm | | 1 | 0 |
| B.Mask | Bottom Solder Mask | Not specified | 0,01 mm | Red | 3,3 | 0 |
| B.Paste | Bottom Solder Paste | | 0 mm | | 1 | 0 |
| B.Silkscreen | Bottom Silk Screen | Not specified | 0 mm | White | 1 | 0 |



LAYER DETAIL

1. FABRICATE PER ANSI/IPC-A-600.IPC-QE-605.IPC-4552 AND IPC-SM-840 SPECIFICATIONS.
2. USE ROHS-COMPLIANT MATERIALS.
3. SOLDERMASK BOTH SIDES OF THE BOARD OVER BARE COPPER WITH MATERIALS PER ANSI/IPC-SM-840.
4. SEE FABRICATION FILES WITH SAME TITLE OR DRAWING, AND REVISION, AS THIS DRAWING
5. APPLY SILKSCREEN TO BOTH SIDES OF THE BOARD USING NON-CONDUCTIVE EPOXY INK
6. SEE SEPARATE DRILL FILE FOR HOLE LOCATIONS

Recommended colors:

- Solder Mask: Red
- Silkscreen: White (expected to be clearly readable on solder mask)
- Base Material: Neutral

Materials:

a. Base material Laminated Epoxy Glass FR-4 with copper traces

- TG 150-160 to TG 170-180 recommended
- Recommended copper thickness 0.6 to 1.6mm
- Min track spacing 3/3mil
- Hole size: 2.2mm +/- 0.25mm
- Thickness per stack-up table
- No edge connector
- Surface finish: HASL lead free

b. Base material aluminium (untested)

- 1 layer
- Copper layer both top and bottom
- Soldermask both sides
- Thermal conductivity: 1.0W/(m*K) to +3.0W/(m*k)
- Thickness: 0.3 to 1.6mm
- Min track spacing: 4/4mil
- No edge connector
- Surface Finish any of HASL lead free, ENIG, EPIG, Ag
- Finished copper: 1 oz Cu